

App. No. 10/708,224  
Amendment dated January 25, 2005  
Reply to Office action of October 25, 2004

**Amendments to the Claims:**

This listing of claims will replace all prior versions, and listings, of claims in the present application.

**Listing of Claims:**

Claim 1 (currently amended): For a semiconductor manufacturing device, a wafer holder comprising:

a substrate having a wafer-carrying side; and

a substrate-supporting shaft, said shaft being joined to said substrate such that a distance  $a$  between the center axis of said shaft and the axial center of said wafer-carrying side of said substrate is 5% or less of the diameter  $L$  of the wafer-carrying side, and said shaft being of a substance whose difference in thermal expansion coefficient with the substrate is  $5 \times 10^{-6}$  K or less, such that temperature distribution in the wafer-carrying side of said substrate is within  $\pm 1.0\%$ .

Claim 2 (original): A wafer holder as set forth in claim 1, being a ceramic susceptor including at least a resistive heating element.

Claim 3 (original): A semiconductor manufacturing device in which a wafer holder as set forth in claim 1 is installed.

Claim 4 (original): A semiconductor manufacturing device in which a wafer holder as set forth in claim 2 is installed.